

IEEE EPS Malaysia: 2021 Technical Talk on Autonomous Driving

(Compiled by Dr Eu Poh Leng)

Dr Eu Poh Leng who is the Director of External Package Innovation in NXP Semiconductors, as well as the Vice Chairman of IEEE EPS Malaysia Chapter, was invited as a Keynote Speaker in the recent Symposium by Yole Development and NCAP on Advanced Packaging for Semiconductors (SYNAPS). In view of the Covid-19 pandemic situation, SYNAPS was held virtually for participants all over the world. The event took place over 3 half-days from 18th to 20th of May 2021, with 3 different categories of topic each day:

- Day 1: Heterogeneous Integration
- Day 2: Fan Out and SiP
- Day 3: Emerging Package and Performance

Dr Eu's sharing took place on Day 3, under the topic of "Advanced Packaging for Autonomous Driving". Total 56 participants watched Dr Eu's presentation live, and 108 participants watched with the replay link. These participants are from > 20 companies worldwide, including Samsung Electronics, ERS Electronic GmbH, Hua Tian Leading Manufacturer, Fraunhofer, Applied Materials Inc., Besi, UTAC, TFME, SPTS Technologies, NCAP, On Semiconductor, ASM and so on. It was a very well-organized event with strong supports from semiconductor industry players internationally.



Event poster for SYNAPS 2021. The poster features a blue and white color scheme with images of autonomous vehicles and a speaker. The text includes: "SYNAPS", "May 20 3pm (GMT+8)", "ADVANCED PACKAGING FOR AUTONOMOUS DRIVING", "Dr. Eu Poh Leng, Director, External Package Innovation, Package Innovation, Chief Technology Office, NXP Semiconductors, 20 MAY 2021", "NXP | SECURE CONNECTIONS FOR A SMARTER WORLD", and logos for NXP, IEEE Electronic Packaging Society, YOLE Development, and NCAP CHINA. Social media icons for LinkedIn, YouTube, Twitter, and Facebook are also present.



Event poster for SYNAPS 2021. The poster features a blue and purple color scheme with a circular graphic and a speaker's portrait. The text includes: "Advanced Packaging for Autonomous Driving", "Dr. Eu Poh Leng, DIRECTOR, EXTERNAL PACKAGE INNOVATION, NXP", "SYNAPS 2021", "May 20 3pm (GMT+8)", "NXP | SECURE CONNECTIONS FOR A SMARTER WORLD", and logos for NXP, IEEE Electronic Packaging Society, YOLE Development, and NCAP CHINA. Social media icons for LinkedIn, YouTube, Twitter, and Facebook are also present.